

| L Number | Hits    | Search Text  | DB  | Time stamp          |
|----------|---------|--|---|---------------------|
| 1        | 20338   | ((photosensitive (photo adj3 sensitive)) with (pi polymer (photo with PI) epoxy))  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/09/25<br>00:51 |
| 2        | 319867  | wafer  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/09/25<br>00:51 |
| 3        | 2330202 | semiconductor chip die ic (integrated adj circuit)   | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/09/25<br>00:51 |
| 4        | 61855   | pad and (bump ball)  | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/09/25<br>00:52 |
| 5        | 120     | ((photosensitive (photo adj3 sensitive)) with (pi polymer (photo with PI) epoxy)) and wafer and (semiconductor chip die ic (integrated adj circuit) ) and (pad and (bump ball)) and solder | USPAT;<br>US-PGPUB;<br>EPO; JPO;<br>DERWENT;<br>IBM TDB | 2003/09/25<br>00:52 |